

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V _{RRM}	400	V
Working Peak Reverse Voltage	V _{RWM}	350	V
DC Blocking Voltage	V _R		V
RMS Reverse Voltage	V _{R(RMS)}	247	V
Forward Continuous Current	I _F	225	mA
Peak Repetitive Forward Current	I _{FRM}	625	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0ms	I _{FSM}	2.0	A
@ t = 1.0s		1.0	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	400	—	—	V	I _R = 150μA
Forward Voltage	V _F	—	—	0.93 1.10 1.29	V	I _F = 20mA I _F = 100mA I _F = 200mA
Reverse Current (Note 6)	I _R	—	—	100 100 5	nA μA μA	V _R = 240V V _R = 240V, T _J = 150°C V _R = 360V
Total Capacitance	C _T	—	0.7	2.0	pF	V _R = 0V, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	—	50	ns	I _F = I _R = 30mA, I _{rr} = 3.0mA, R _L = 100Ω

- Notes:
- Part mounted on polyimide substrate PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 - Short duration pulse test used to minimize self-heating effect.

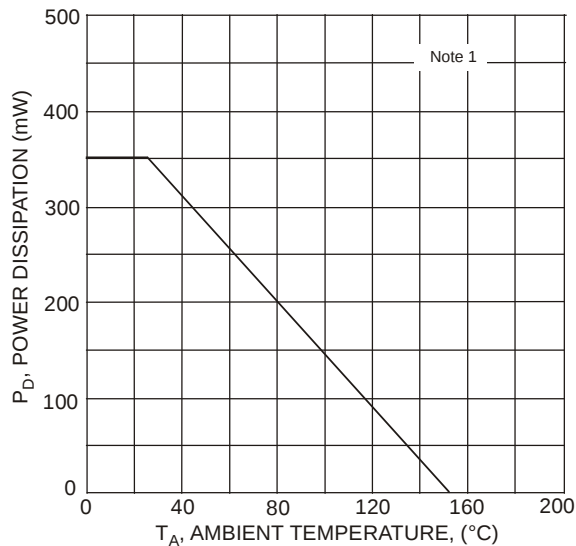


Fig. 1 Power Derating Curve, Total Package

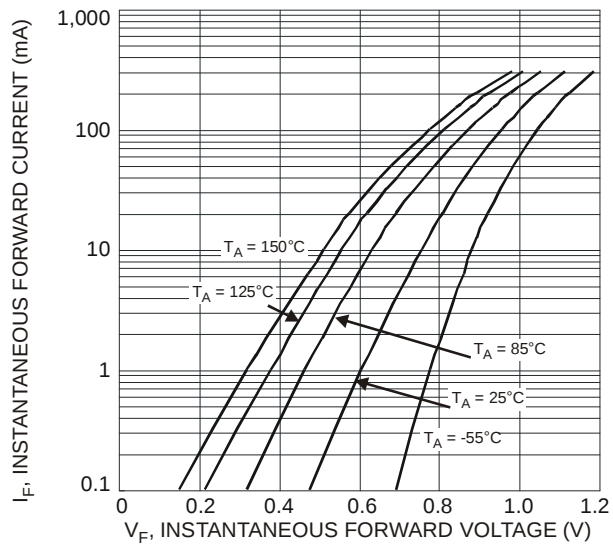


Fig. 2 Typical Forward Characteristics, Per Element

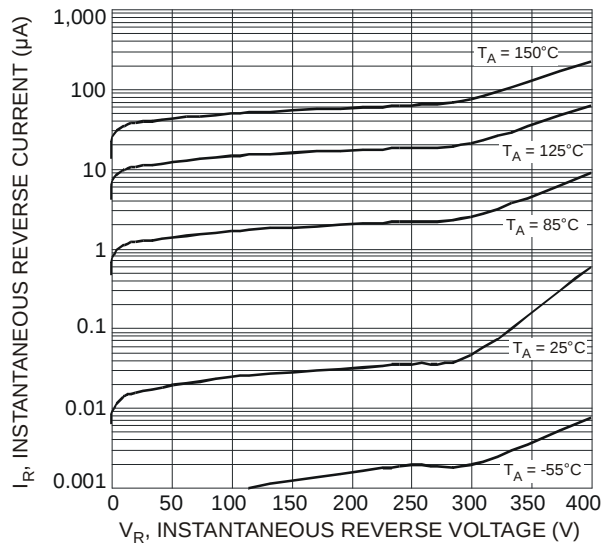


Fig. 3 Typical Reverse Characteristics, Per Element

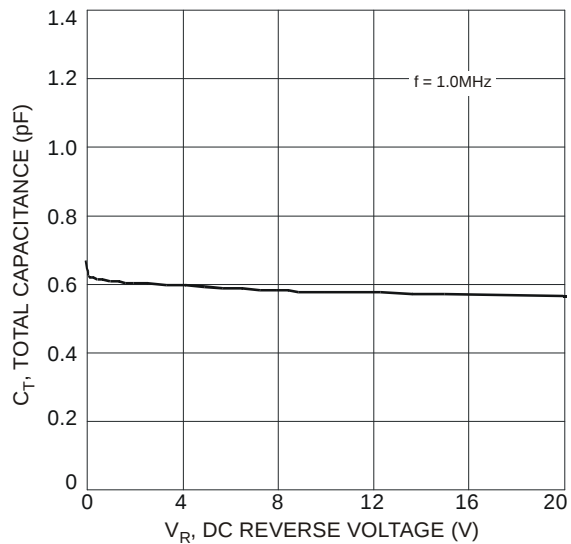
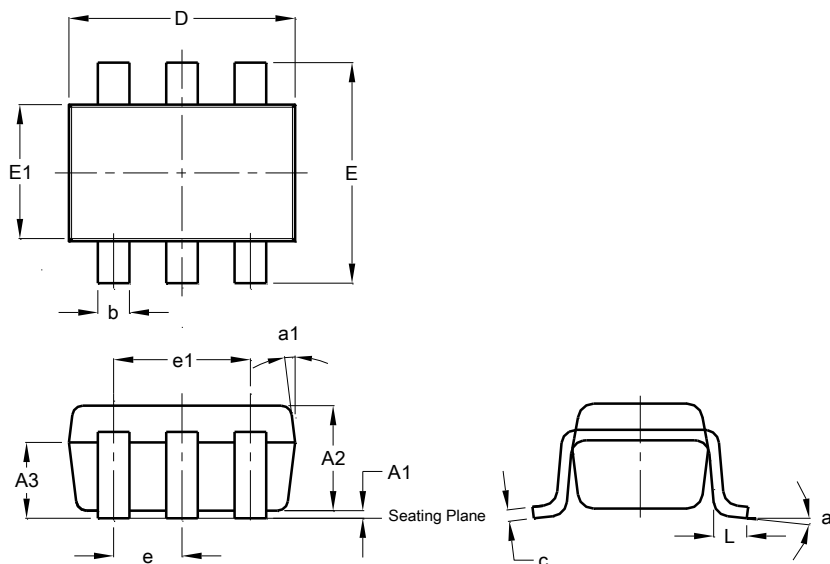


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

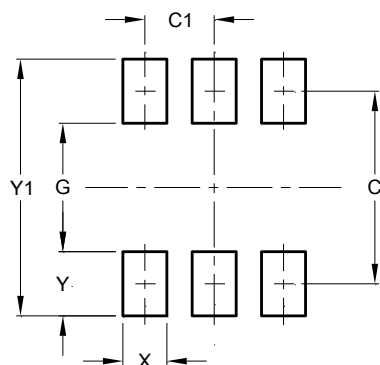
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



SOT26 / SC74R			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

Application Examples

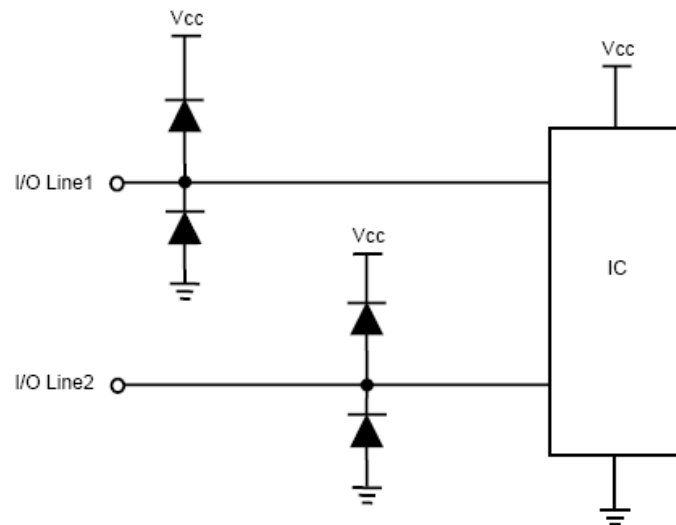


Figure 1. Typical Rail-to-Rail Protection

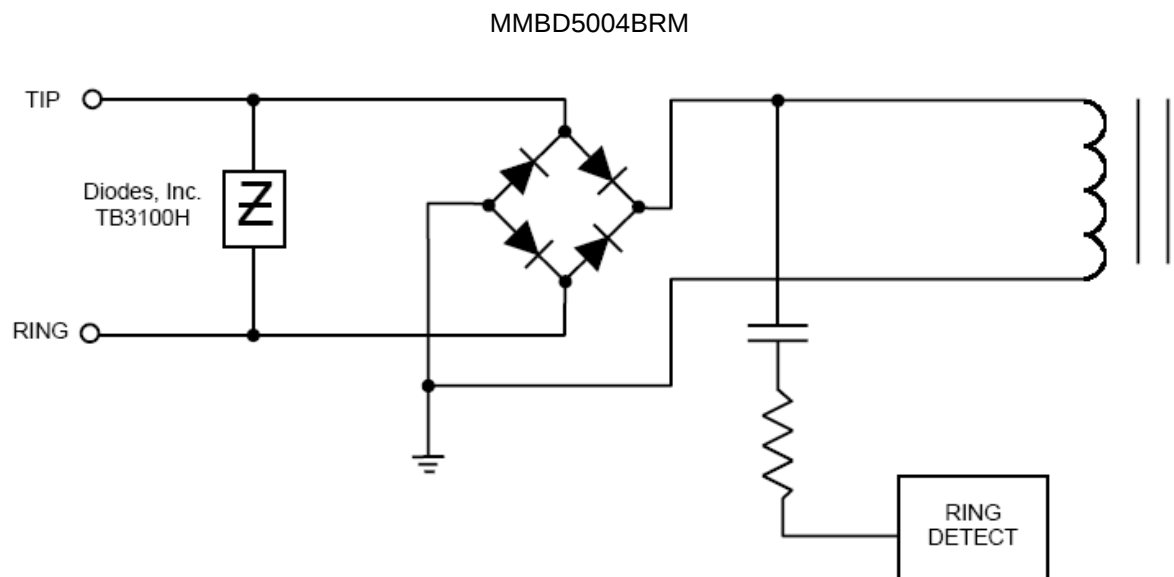


Figure 2. Typical Transformer Coupled Tip and Ring Interface

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